Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Withdrawn) A method of attenuating scattering electro-magnetic waves present on metallized areas within a mobile phone that are caused by components within the mobile phone, the method comprising varying the metallization pattern near an edge of the metallized area such that electric current due to scattering electro-magnetic waves present on the metallized area encounters higher impedances as it approaches the edge of the metallized area.

2. (Currently Amended) A method of attenuating scattering electro-magnetic waves present on metallized areas within a mobile phone ~~that are~~ caused by components within the mobile phone, the method comprising placing discrete components near an edge of the metallized ~~area~~areas, the discrete components obstructing a current path of scattering electro-magnetic waves present on the metallized areas such that electric current due to the scattering electro-magnetic waves present on the metallized ~~area~~ areas encounters higher impedances as the scattering electro-magnetic waves flow through~~due to~~ the discrete components near the edge of the metallized ~~area~~areas, the ~~high~~ higher impedances attenuating the scattering electro-magnetic waves emitted from the edge of the metallized areas.

3. (Original) The method of claim 2 wherein the discrete components include resistors.

4. (Original) The method of claim 2 wherein the discrete components include capacitors.

5. (Original) The method of claim 2 wherein the discrete components include inductors.

6. (Original) The method of claim 2 wherein the discrete components include a combination of resistors, capacitors, and inductors.

7. (Withdrawn) A method of attenuating scattering electro-magnetic waves present on metallized areas within a mobile phone that are caused by components within the mobile phone, the method comprising placing capacitive gaps and inductive lines near an edge of the metallized area such that electric current due to scattering electro-magnetic waves present on the metallized area encounters higher impedances due to the capacitive gaps and inductive lines near the edge of the metallized area.

8. (Withdrawn) A method of attenuating scattering electro-magnetic waves present on metallized areas within a mobile phone that are caused by components within the mobile phone, the method comprising placing multiple varying layers of conductivity near an edge of the metallized area such that electric current due to scattering electro-magnetic waves present on the metallized area encounters higher impedances due to the multiple varying layers of conductivity near the edge of the metallized area.

9. (Withdrawn) A mobile phone that attenuates scattering electro-magnetic waves present on metallized areas within the mobile phone that are caused by components within the mobile phone, the mobile phone comprising:
a varied metallization pattern near an edge of metallized areas such that electric current due to scattering electro-magnetic waves present on the metallized areas encounters higher impedances as it approaches the edge of the metallized areas.

10. (Currently Amended) A mobile phone that attenuates scattering electro-magnetic waves present on metallized areas within the mobile phone ~~that are~~ caused by components within the mobile phone, the mobile phone comprising:

discrete components placed near an edge of metallized areas, the discrete components obstructing a current path of scattering electro-magnetic waves present on the metallized areas such that electric current due to the scattering electro-magnetic waves present on the metallized areas encounters higher impedances as the scattering electro-magnetic waves flow through ~~due to~~ the discrete components near the edge of the metallized areas, the high impedances attenuating the scattering electro-magnetic waves emitted from the edge of the metallized areas.

11. (Original) The mobile phone of claim 10 wherein the discrete components include resistors.

12. (Original) The mobile phone of claim 10 wherein the discrete components include capacitors.

13. (Original) The mobile phone of claim 10 wherein the discrete components include inductors.

14. (Original) The mobile phone of claim 10 wherein the discrete components include a combination of resistors, capacitors, and inductors.

15. (Withdrawn) A mobile phone that attenuates scattering electro-magnetic waves present on metallized areas within the mobile phone that are caused by components within the mobile phone, the mobile phone comprising:
capacitive gaps and inductive lines placed near an edge of metallized areas such that electric current due to scattering electro-magnetic waves present on the metallized areas encounters higher impedances due to the capacitive gaps and inductive lines near the edge of the metallized areas.

16. (Withdrawn) A mobile phone that attenuates scattering electro-magnetic waves present on metallized areas within the mobile phone that are caused by components within the mobile phone, the mobile phone comprising:

multiple varying layers of conductivity placed near an edge of metallized areas such that electric current due to scattering electro-magnetic waves present on the metallized areas encounters higher impedances due to the multiple varying layers of conductivity near the edge of the metallized areas.